APRIL 1971 - REVISED JUNE 2000

- 8 A Continuous On-State Current
- 80 A Surge-Current
- Glass Passivated Wafer
- 400 V to 800 V Off-State Voltage
- Max I<sub>GT</sub> of 20 mA

w.DataSheet4U.com

 Image: To-220 PACKAGE (TOP VIEW)

 K
 1

 A
 2

 G
 3

Pin 2 is in electrical contact with the mounting base.

MDC1ACA

### absolute maximum ratings over operating case temperature (unless otherwise noted)

RATING			VALUE	UNIT	
	TIC116D		400		
Repetitive peak off-state voltage	TIC116M	V	600	v	
	TIC116S	V <sub>DRM</sub>	700		
	TIC116N		800		
Repetitive peak reverse voltage	TIC116D		400	v	
	TIC116M	V	600		
	TIC116S	V <sub>RRM</sub>	700		
	TIC116N		800		
Continuous on-state current at (or below) 70°C case temperature (see Note 1)			8	А	
Average on-state current (180° conduction angle) at (or below) 70°C case temperature			5	Α	
(see Note 2)		I <sub>T(AV)</sub>	5	A	
Surge on-state current at (or below) 25°C case temperature (see Note 3)		I <sub>TM</sub>	80	А	
Peak positive gate current (pulse width $\leq$ 300 $\mu$ s)		I <sub>GM</sub>	3	А	
Peak gate power dissipation (pulse width $\leq$ 300 $\mu$ s)		P <sub>GM</sub>	5	W	
Average gate power dissipation (see Note 4)		P <sub>G(AV)</sub>	1	W	
Operating case temperature range			-40 to +110	°C	
Storage temperature range			-40 to +125	°C	
Lead temperature 1.6 mm from case for 10 seconds		ΤL	230	°C	

NOTES: 1. These values apply for continuous dc operation with resistive load. Above 70°C derate linearly to zero at 110°C.

2. This value may be applied continuously under single phase 50 Hz half-sine-wave operation with resistive load. Above 70°C derate linearly to zero at 110°C.

3. This value applies for one 50 Hz half-sine-wave when the device is operating at (or below) the rated value of peak reverse voltage and on-state current. Surge may be repeated after the device has returned to original thermal equilibrium.

4. This value applies for a maximum averaging time of 20 ms.



Information is current as of publication date. Products conform to specifications in accordance with the terms of Power Innovations standard warranty. Production processing does not necessarily include testing of all parameters.



APRIL 1971 - REVISED JUNE 2000

### electrical characteristics at 25°C case temperature (unless otherwise noted)

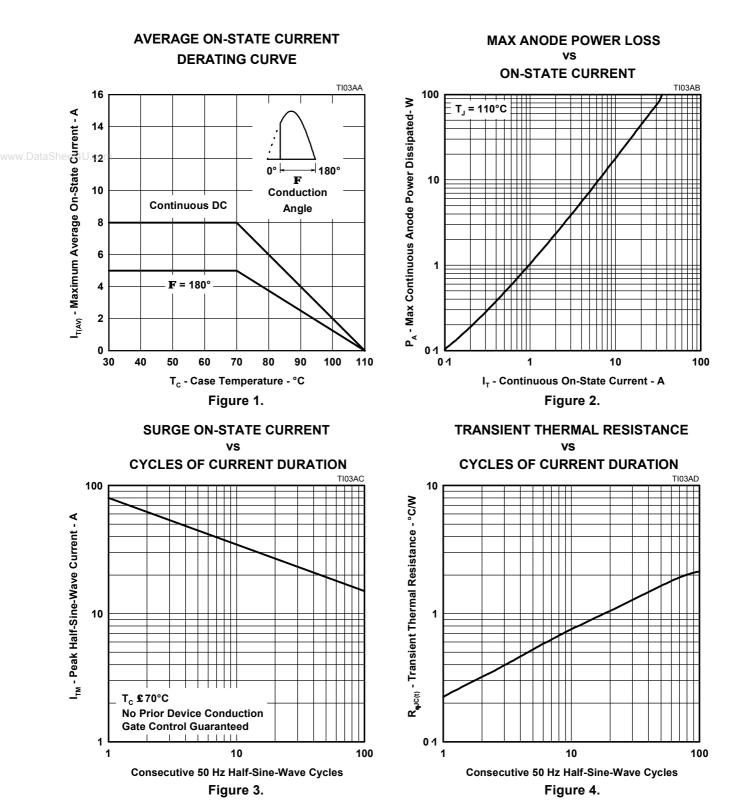
PARAMETER		TEST CONDITIONS		MIN	ТҮР	MAX	UNIT	
I <sub>DRM</sub>	Repetitive peak off-state current	$V_D = rated V_{DRM}$		$T_{C} = 110^{\circ}C$			2	mA
I <sub>RRM</sub>	Repetitive peak reverse current	$V_{R} = rated V_{RRM}$	$I_{G} = 0$	$T_{C} = 110^{\circ}C$			2	mA
I <sub>GT</sub>	Gate trigger current	V <sub>AA</sub> = 12 V	R <sub>L</sub> = 100 Ω	t <sub>p(g)</sub> ≥ 20 μs		8	20	mA
V <sub>GT</sub> a\$heet4U.cc	Gate trigger voltage	V <sub>AA</sub> = 12 V t <sub>p(g)</sub> ≥ 20 μs	R <sub>L</sub> = 100 Ω	$T_{C} = -40^{\circ}C$			2.5	
		$V_{AA} = 12 V$ $t_{p(g)} \ge 20 \ \mu s$	R <sub>L</sub> = 100 Ω			0.8	1.5	V
		$V_{AA} = 12 V$ $t_{p(g)} \ge 20 \ \mu s$	R <sub>L</sub> = 100 Ω	T <sub>C</sub> = 110°C	0.2			
	Holding current	$V_{AA} = 12 V$ Initiating I <sub>T</sub> = 100 mA		$T_{\rm C}$ = - 40°C			100	mA
		$V_{AA} = 12 V$ Initiating I <sub>T</sub> = 100 mA					40	ША
V <sub>T</sub>	On-state voltage	I <sub>T</sub> = 8 A	(see Note 5)				1.7	V
dv/dt	Critical rate of rise of off-state voltage	$V_D = rated V_D$	$I_{\rm G}=0$	$T_{C} = 110^{\circ}C$		400		V/µs

NOTE 5: This parameter must be measured using pulse techniques,  $t_p = 300 \ \mu$ s, duty cycle  $\le 2 \ \%$ . Voltage sensing-contacts, separate from the current carrying contacts, are located within 3.2 mm from the device body.

### thermal characteristics

PARAMETER		MIN	ТҮР	MAX	UNIT
$R_{\theta JC}$	Junction to case thermal resistance			3	°C/W
$R_{\theta JA}$	Junction to free air thermal resistance			62.5	°C/W

APRIL 1971 - REVISED JUNE 2000

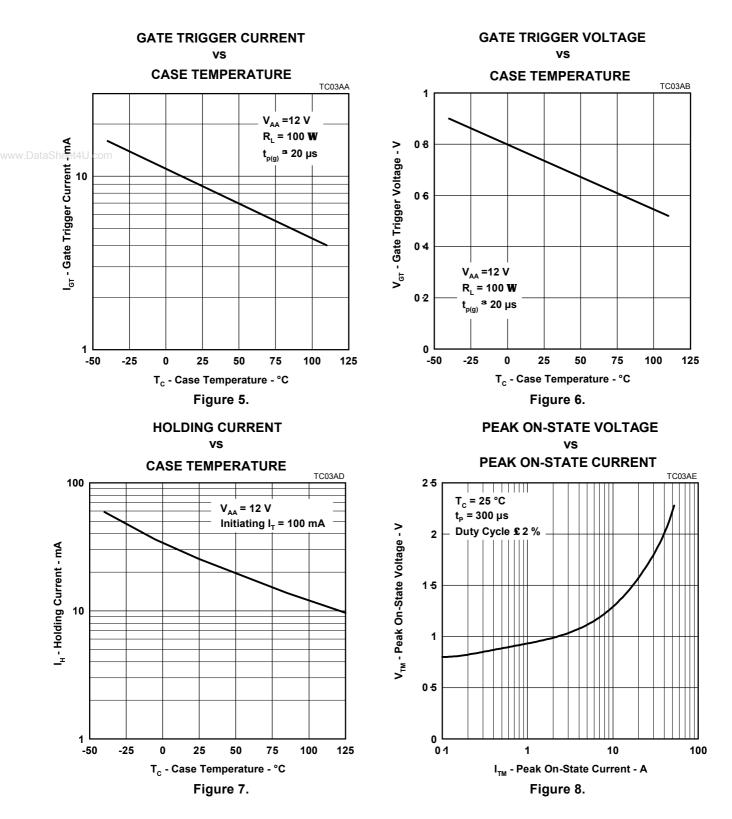


### THERMAL INFORMATION



APRIL 1971 - REVISED JUNE 2000

### **TYPICAL CHARACTERISTICS**



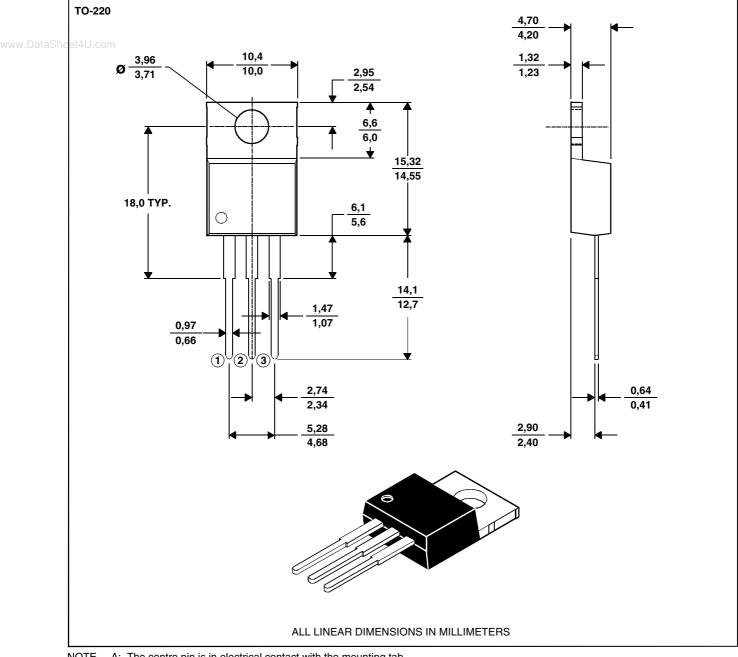
APRIL 1971 - REVISED JUNE 2000

## MECHANICAL DATA

## TO-220

## 3-pin plastic flange-mount package

This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



NOTE A: The centre pin is in electrical contact with the mounting tab.



APRIL 1971 - REVISED JUNE 2000

ww.DataSheet4U.com

### **IMPORTANT NOTICE**

Power Innovations Limited (PI) reserves the right to make changes to its products or to discontinue any semiconductor product or service without notice, and advises its customers to verify, before placing orders, that the information being relied on is current.

PI warrants performance of its semiconductor products to the specifications applicable at the time of sale in accordance with PI's standard warranty. Testing and other quality control techniques are utilized to the extent PI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except as mandated by government requirements.

PI accepts no liability for applications assistance, customer product design, software performance, or infringement of patents or services described herein. Nor is any license, either express or implied, granted under any patent right, copyright, design right, or other intellectual property right of PI covering or relating to any combination, machine, or process in which such semiconductor products or services might be or are used.

PI SEMICONDUCTOR PRODUCTS ARE NOT DESIGNED, INTENDED, AUTHORIZED, OR WARRANTED TO BE SUITABLE FOR USE IN LIFE-SUPPORT APPLICATIONS, DEVICES OR SYSTEMS.

Copyright © 2000, Power Innovations Limited